L	Hits	Search Text	DB	Time stamp
Number				_
1	1	(fang-jui-hua chung-cheng-hui	USPAT;	2004/03/03
_		lu-chia-hui).in. and barrier	US-PGPUB;	09:29
			EPO;	
			DERWENT	
2	10	(second adj1 barrier) same ((anneal\$3	USPAT;	2004/03/03
		treat\$3 heat\$3) with (nitrogen (nitrous	US-PGPUB	12:51
		adj1 oxide))).bi.		
3	604	(second adj1 barrier) with ("Cu/Al/Si"	USPAT;	2004/03/03
		"Cu/Al" wiring conduct\$3).bi.	US-PGPUB	10:30
4	418	(second adj1 barrier) with ("Cu/Al/Si"	USPAT	2004/03/03
		"Cu/Al" wiring conduct\$3).bi.	'	10:30
5	107	(((metal conductive) adjl (wiring layer	USPAT;	2004/03/03
		film)) with barrier) same ((anneal\$3	US-PGPUB	12:01
		treat\$3) with nitrogen).bi.		
6	6	007304.ap.	USPAT;	2004/03/03
			US-PGPUB	12:01
7	35180	(anneal\$3 treat\$3 heat\$3) with (bak\$3	USPAT;	2004/03/03
		(ion adj1 bump\$3) quench\$3).bi.	US-PGPUB	12:52
8	340	((anneal\$3 treat\$3 heat\$3) with (bak\$3	USPAT;	2004/03/03
	Ì	(ion adj1 bump\$3) quench\$3)) same	US-PGPUB	13:30
		barrier.bi.		
9	0	( \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	USPAT;	2004/03/03
		(ion adj1 bump\$3)) with quench\$3) same	US-PGPUB	13:15
		barrier.bi.		
10	0		USPAT;	2004/03/03
		(ion adj1 bump\$3)) with quench\$3) and	US-PGPUB	13:15
	_	barrier.bi.	1	0004400400
13	0	(quench\$3 and bak43 and barrier).bi.	USPAT;	2004/03/03
			US-PGPUB	13:17
14	1262	(quench\$3 and bak\$3 and barrier).bi.	USPAT;	2004/03/03
4.5		1 142	US-PGPUB	13:18
15	58	(quench\$3 same bak\$3) and barrier.bi.	USPAT;	2004/03/03
1.6	1	//	US-PGPUB USPAT;	13:18 2004/03/03
16	10	((anneal\$3 treat\$3 heat\$3) with nitrogen	USPAT; US-PGPUB	13:27
17	150	with quench\$3) same barrier.bi.	USPAT;	2004/03/03
17	158	((anneal\$3 treat\$3 heat\$3) with quench\$3)	USPAT; US-PGPUB	13:30
1.0	1.00	same barrier.bi.	USPAT;	2004/03/03
18	162	((anneal\$3 treat\$5 heat\$3) with quench\$3)	USPAT; US-PGPUB	13:31
		same barrier.bi.	J US-PGPUB	13.31